



## 3D Nanostructured Materials and Devices

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Deadline for manuscript  
submissions:

**closed (25 February 2021)**

### Message from the Guest Editor

Dear Colleagues,

With the great development of nanofabrication technology, we have been able to create high levels of 3D nanostructures that could not be achieved previously. In particular, new or superphysical properties emerging from 3D nanostructures have attracted the attention of many researchers exploring advanced materials and next-generation devices.

This Special Issue will consist of comprehensive review and original research articles featuring important and recent developments in 3D nanostructured materials and devices. Subject areas include but are not limited to advanced 3D nanofabrication, 3D nanostructures and their properties, 3D material analysis and simulation, functional materials and device applications with 3D nanostructures, etc. Authors who are experts in these fields of study are invited to submit their contributions for this Special Issue up to the end of April 2020.





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## Editor-in-Chief

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## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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